

2.5G BASE With POE Plus Dual Port Isolation Transformer Module MODEL NO.: XF-GD482T001

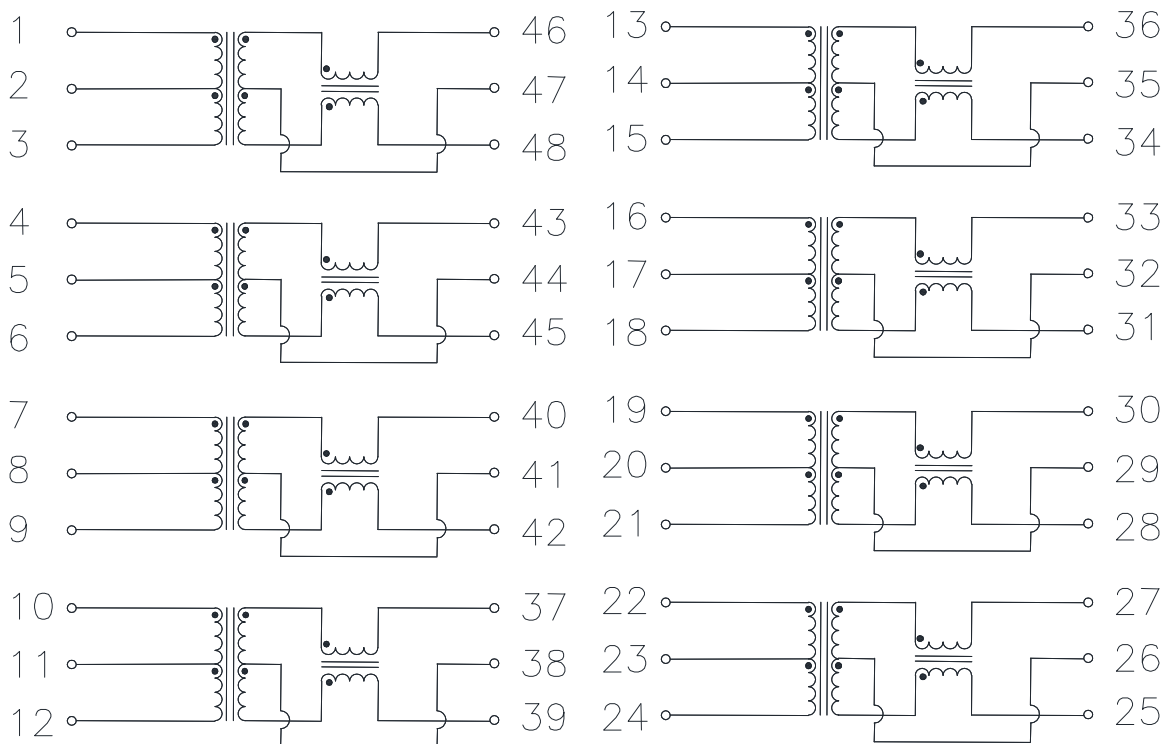
Feature:

1. RoHS Compliant
2. RoHS Peak Solder Rating 260°C/ 3~5 Sec.
3. Not Use The Controlled Substances Defined in SS-00259
4. Designed To Meet IR Requirement
5. Operating Temperature : -40°C~ +85°C
6. OCL : 350 uH Min @100kHz ,100mV 8mA VDC
7. Meets IEEE 802.3 at specification with 1.2A max. current capability.

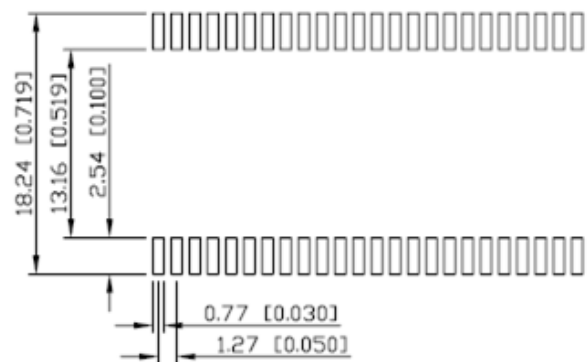
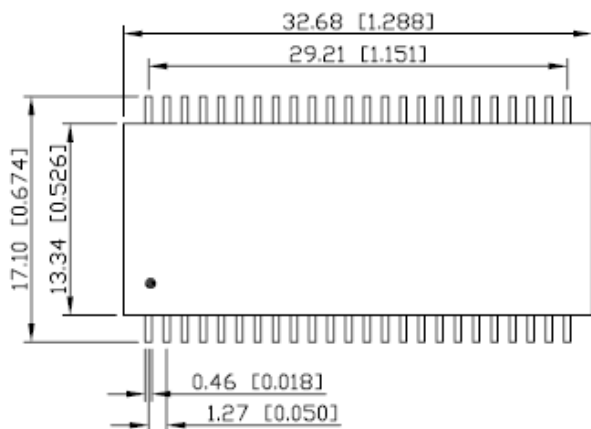
Specifications @ 25°C

Insertion Loss (MHz) (dB MAX)			Return Loss (MHz) (dB MIN)			Cross talk (MHz) (dB MIN)		Common Mode Rejection (MHz) (dB TYP)		Hi-Pot (Vrms MIN)
1-100	100-125	125-250	1-40	40-100	100-125	1-100	100-125	1-100	100-125	1500
-1.0	-1.5	-2.5	-16	-10	-6	-30	-25	-30	-25	

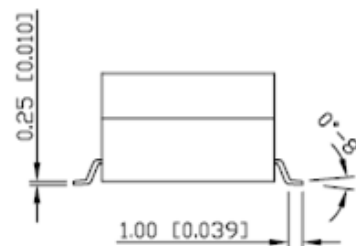
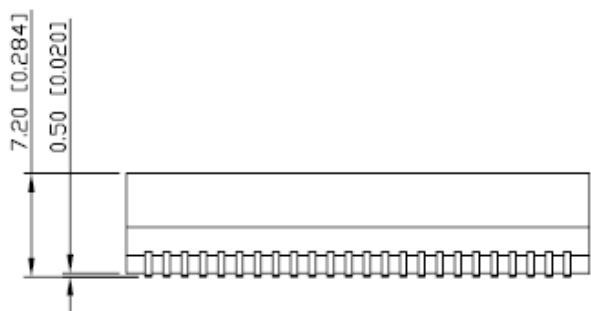
Schematic:



Dimension : mm ±0.25



SUGGESTED PAD LAYOUT



Marking :



Remark:

XMULTIPLE=LOGO

XF-GD482T001=PART NUMBER

YYWW DATE CODE , YY=YEAR · WW=WEEK

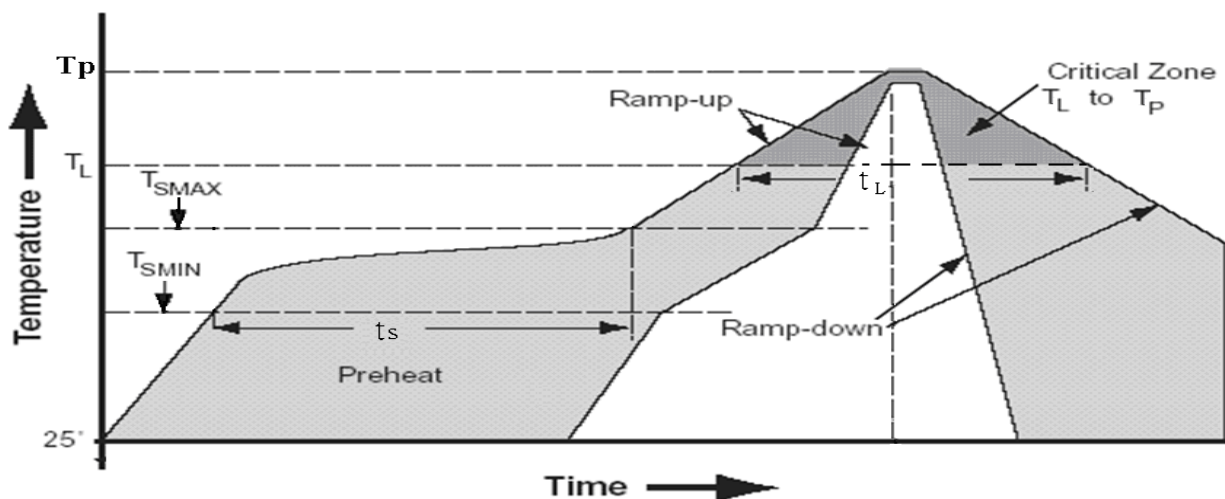
MODEL NO.: XF-GD482T001

Solder Reflow profile for Lead-Free packages. Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (t_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	200 °C 60-90 sec	
Peak Temperature (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile :





MODEL NO.: XF-GD482T001

Packing :

1 reel consists of 300pcs.

1 box consists of 5 reels